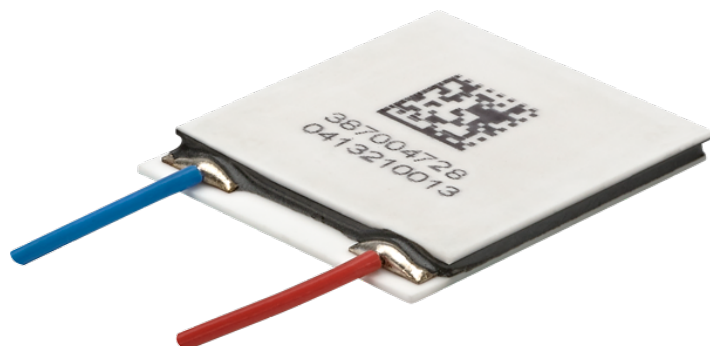


UltraTEC™ UTX Series Thermoelectric Cooler

The UTX6-12-F2-4040-TB-EP-W6 is a high-performance thermoelectric cooler that is assembled with advanced thermoelectric materials and can boost cooling capacity by up to 10%. The UltraTEC UTX Series features a higher thermal insulating barrier when compared to standard materials creating a maximum temperature differential (ΔT) of 71.7 °C at $Q_c = 0$. It has a maximum Q_c of 51.4 Watts when $\Delta T = 0$.

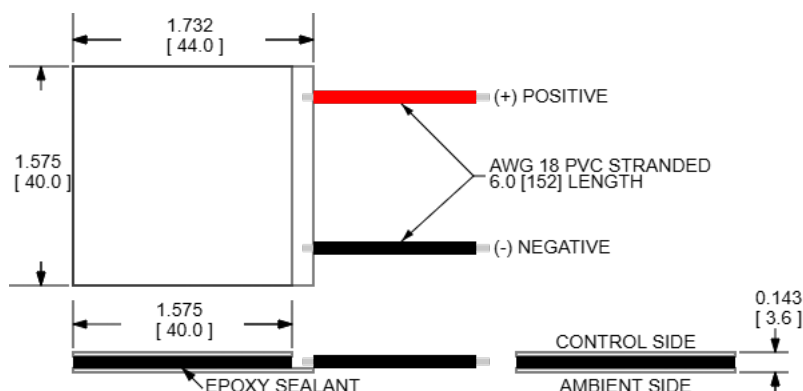


Features

- High heat pump density
- Precise temperature control
- Reliable solid-state operation
- No sound or vibration
- DC operation
- RoHS-compliant

Applications

- Spot Cooling for Industrial Lasers & Optics
- Thermoelectric Cooling for Projection Lasers



CERAMIC MATERIAL: Al_2O_3

SOLDER CONSTRUCTION: 138°C, BiSn

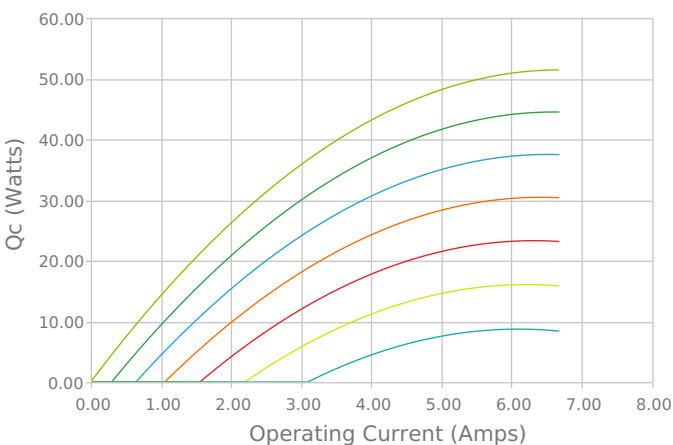
INCHES [MM]

Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

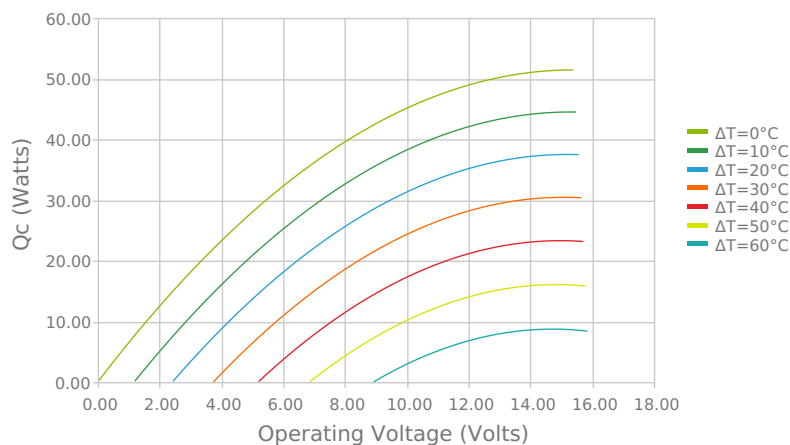
ELECTRICAL AND THERMAL PERFORMANCE

For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the AMBIENT side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

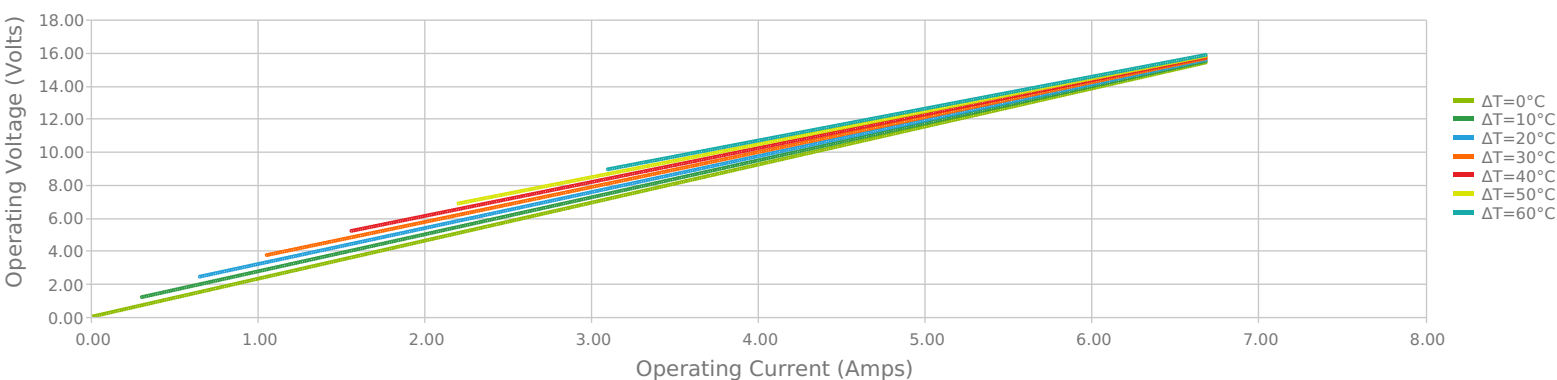
Heat Pumped at Cold Side
 $T_{hot} = 27\text{ °C}$



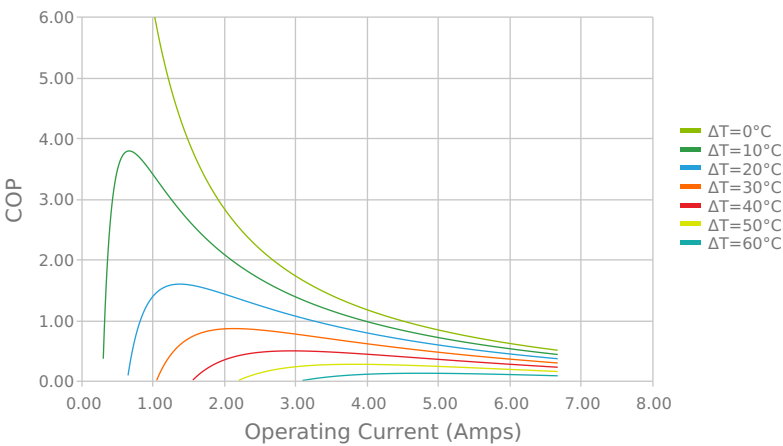
Heat Pumped at Cold Side
 $T_{hot} = 27\text{ °C}$



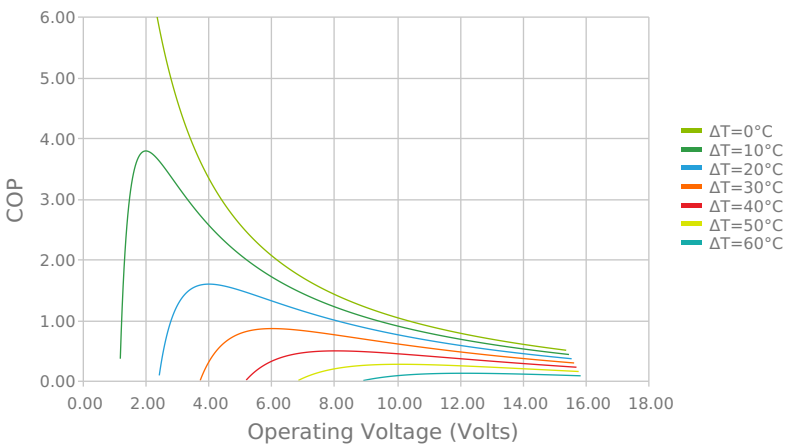
Current vs Voltage (I vs V)
 $T_{hot} = 27\text{ °C}$



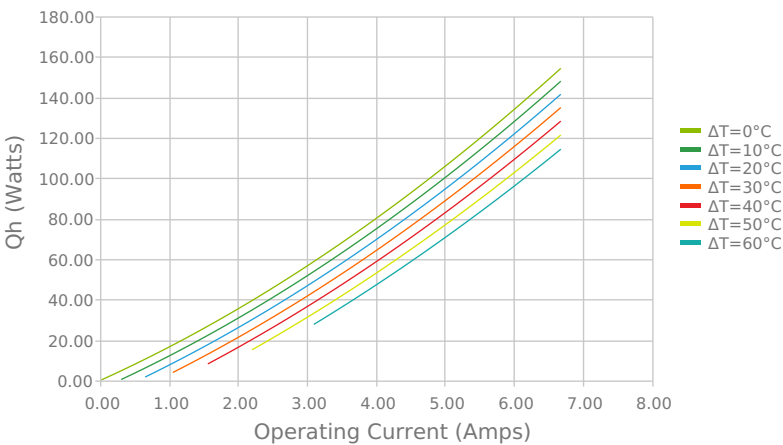
Coefficient of Performance (COP = Q_c/P_{in})
 $T_{hot} = 27\text{ }^{\circ}\text{C}$



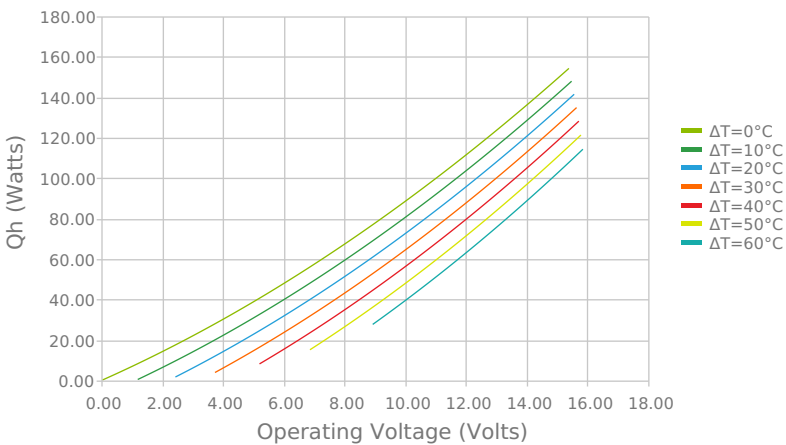
Coefficient of Performance (COP = Q_c/P_{in})
 $T_{hot} = 27\text{ }^{\circ}\text{C}$



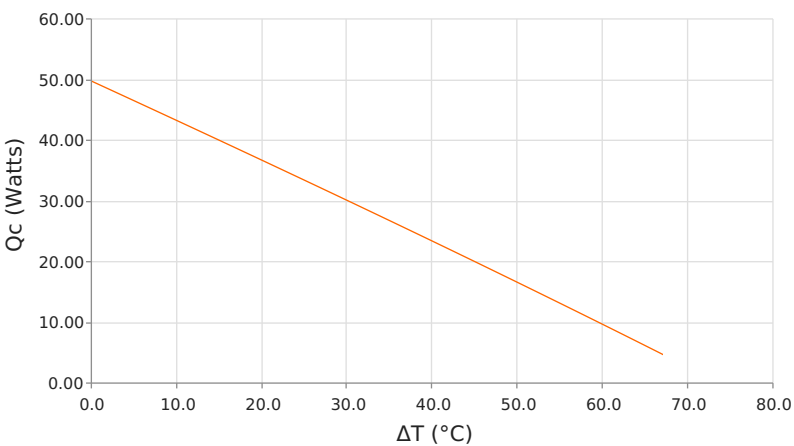
Total Heat Dissipated at Hot Side ($Q_h=Q_c+P_{in}$)
 $T_{hot} = 27\text{ }^{\circ}\text{C}$



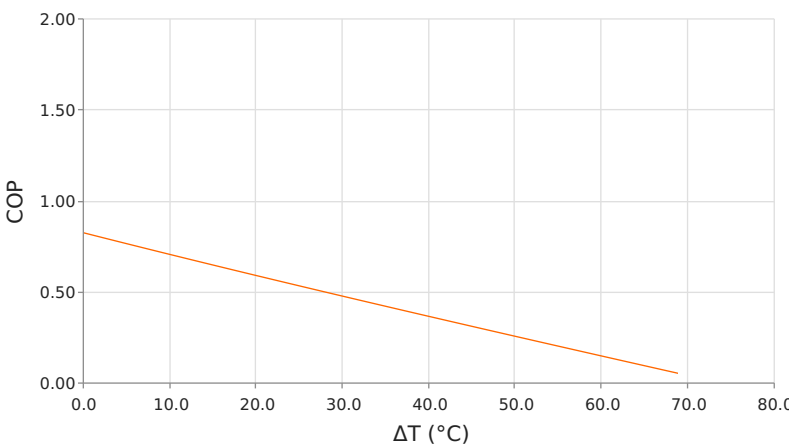
Total Heat Dissipated at Hot Side ($Q_h=Q_c+P_{in}$)
 $T_{hot} = 27\text{ }^{\circ}\text{C}$



Heat Pumped at Cold Side (Q_c)
 $T_{hot} = 35\text{ }^{\circ}\text{C}$ | $I_{operating} = 5\text{ Amps}$



Coefficient of Performance (COP = Q_c/P_{in})
 $T_{hot} = 35\text{ }^{\circ}\text{C}$ | $I_{operating} = 5\text{ Amps}$



SPECIFICATIONS

Hot Side Temperature	27.0 °C	35.0 °C	50.0 °C
Qcmax (ΔT = 0)	51.4 Watts	52.9 Watts	55.3 Watts
ΔTmax (Qc = 0)	71.7°C	74.8°C	80.4°C
Imax (I @ ΔTmax)	6.0 Amps	5.9 Amps	5.8 Amps
Vmax (V @ ΔTmax)	14.6 Volts	15.1 Volts	16.2 Volts
Module Resistance	2.30 Ohms	2.40 Ohms	2.59 Ohms
Max Operating Temperature	80 °C		
Weight	20.0 gram(s)		

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
TB	3.632 ±0.013 mm 0.143 ± 0.0005 in	0.013 mm / 0.013 mm 0.0005 in / 0.0005 in	Lapped	Lapped	152.4 mm 6.00 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
EP	Epoxy	Black	-55 to 150°C	Low density syntactic foam epoxy encapsulant

NOTES

1.

Max operating temperature: 80°C
2.

Do not exceed Imax or Vmax when operating module
3.

Reference assembly guidelines for recommended installation
4.

Recommended to be used with a liquid heat exchanger on the hot side

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